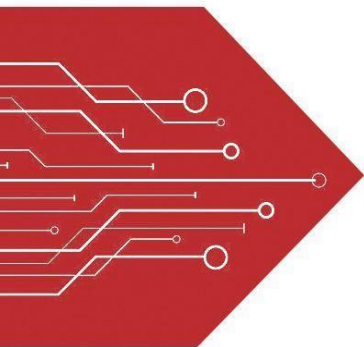


MSKSEMI

SEMICONDUCTOR



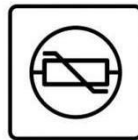
ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet

www.msksemi.com

FEATURES

- For surface mounted applications
- Glass Passivated Chip Junction
- Fast reverse recovery time
- Ideal for automated placement



SOD-323



PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

MARK:T3

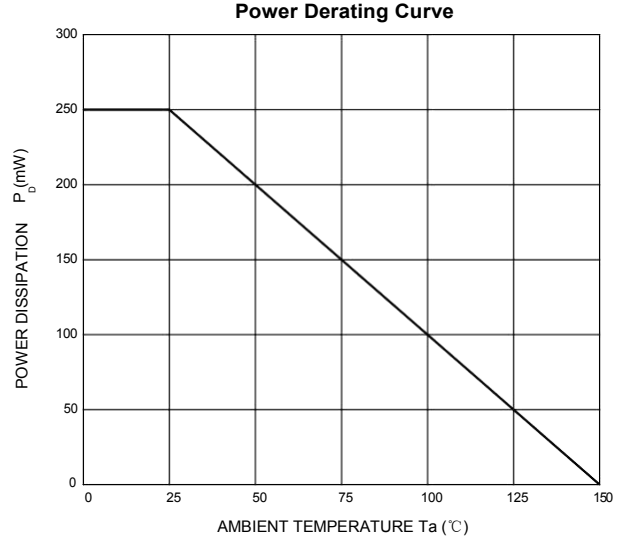
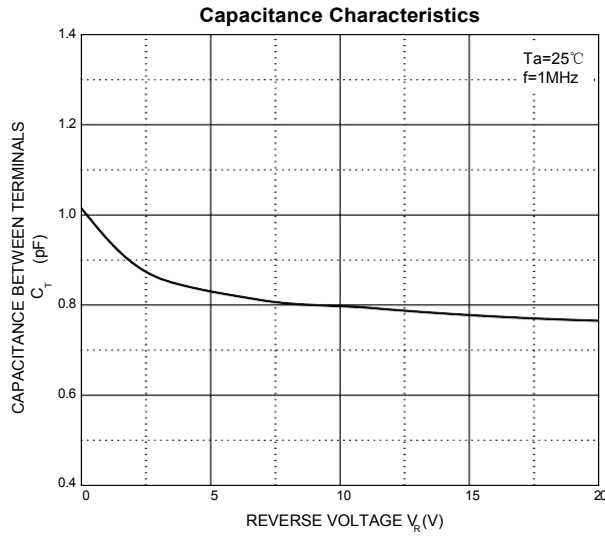
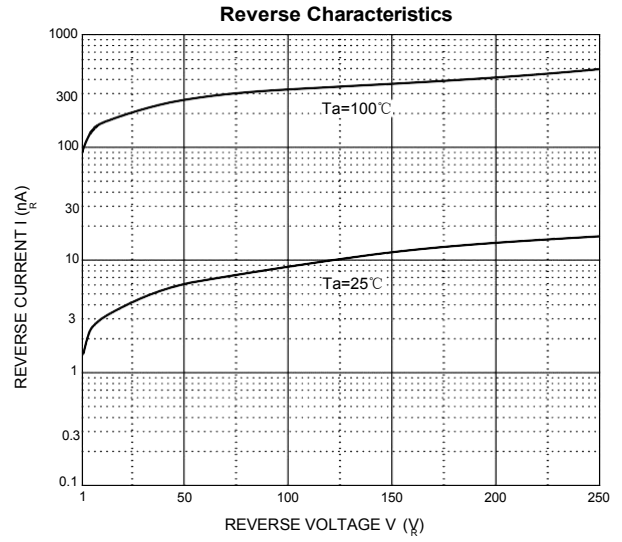
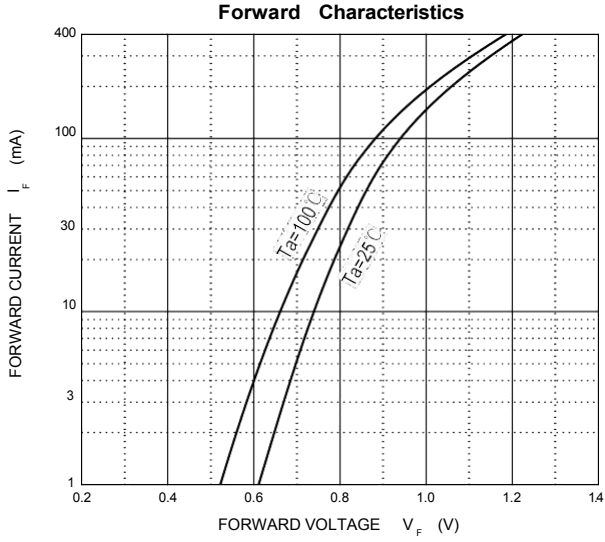
Absolute Maximum Ratings at 25 °C

Parameter	Symbols	BAV21WS	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	250	V
Maximum RMS voltage	V_{RMS}	200	V
Continuous Forward Current	I_F	250	mA
Repetitive Peak Forward Current	I_{FRM}	625	mA
Non-reptitive Peak Forward Surge Current at 1s at 1ms at 1 us	I_{FSM}	1 3 9	A
Total Power Dissipation	P_{tot}	500	mW
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

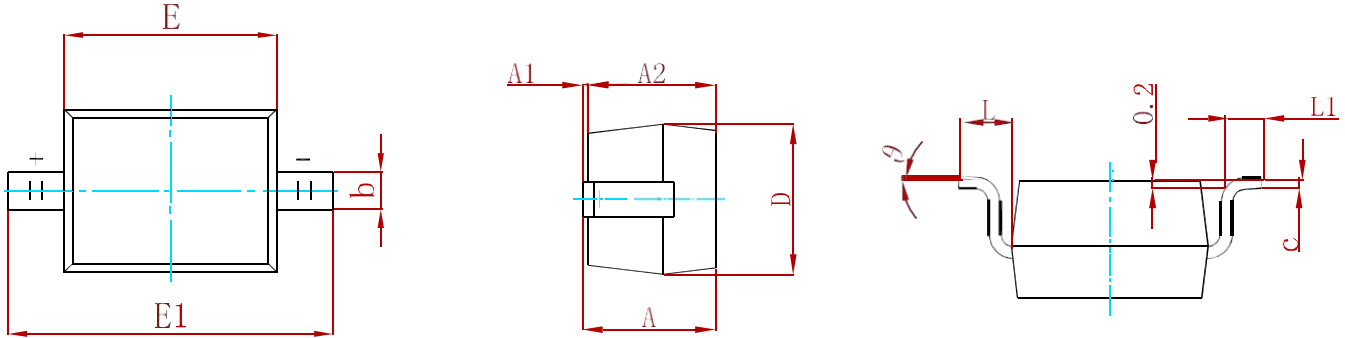
Characteristics at $T_a = 25\text{ °C}$

Parameter	Symbols	BAV21WS	Units
Reverse Breakdown Voltage at $I_R=100\mu A$	$V_{(BR)R}$	250	V
Maximum Forward Voltage at 100 mA at 200 mA	V_F	1.00 1.25	V
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_a = 25\text{ °C}$ $T_a = 150\text{ °C}$	I_R	0.1 100	μA
Typical Junction Capacitance at $V_R=4V, f=1MHz$	C_j	5	pF
Maximum Reverse Recovery Time ⁽¹⁾	t_{rr}	50	ns

(1) Measured with $I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$

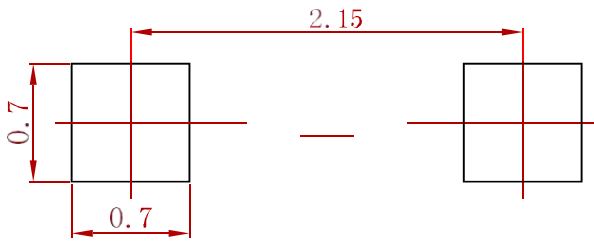


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



- Note:**
1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BAV21WS-MS	SOD-323	3000

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